



PATENT APPLICATION

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

Applicant: Hyun-Woo Kim et al. Examiner: Amanda C. Walke
Serial No: 10/787,368 Group Art Unit: 1752
Filed: February 26, 2004 Docket: 8028-42 (SPX200304-0017US)
For: **METHOD OF FORMING AN UNDERLAYER OF A BI-LAYER RESIST
FILM AND METHOD OF FABRICATING A SEMICONDUCTOR
DEVICE USING THE SAME**

Mail Stop AF
Commissioner for Patents
P.O. Box 1450
Alexandria, VA 22313-1450

REPLY

Sir:

In response to the Office Action dated February 10, 2005, finally rejecting all of the pending claims, please reconsider the above-identified application as follows:

Listing of Claims begins on page 2 of this paper.


Remarks/Arguments begin on page 9 of this paper.

Reconsideration is respectfully requested to place this application in condition for allowance or better condition for appeal.

CERTIFICATE OF MAILING 37 C.F.R. §1.8(a)

I hereby certify that this correspondence (and any document referred to as being attached or enclosed) is being deposited with the United States Postal Service as first class mail, postage paid in an envelope addressed to: Commissioner for Patents, P.O. Box 1450 Alexandria, VA 22313-1450, on April 11, 2005.

Dated: April 11, 2005


Bernard Lau

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